

1           ABSTRACT OF THE DISCLOSURE UNDER 37 C.F.R. §1.72(b)

2

3           Selective application of solder bumps in an integrated circuit package.

4       Solder bumps are selectively applied in a solder bump integrated circuit  
5       packaging process so that portions of a circuit can be effectively disabled.

6       The bumps may be selectively applied either to a die or to the substrate using  
7       multiple solder masks, one for each pattern of solder bumps desired or can be  
8       otherwise applied in multiple patterns depending upon which portions of the  
9       circuitry are to be active and which are to be disabled.

10

11